



(Green) QFN Package RELIABILITY QUALIFICATION REPORT SUMMARY

Technology Description	Green (Lead and Halide Free) Quad Flat No Lead Pack in 32 and 24 LD with thermal exposed pad.
Qualification Vehicle	QFN32 8x8

QFN Packaging Information	
UL flammability class	UL 94 V-0 & ≥ 28%
Lead Frame Material	Copper
Die Attach	Sumitomo CRM 1076DS
Mold compound	Hitachi CEL 9220HFA
Bond Wire	Gold
Lead Finish	Matte Tin (Sn)

Factory Locations	
Wafer Fabrication	CSM AMD SONY UMC
Assembly	ASE, Malaysia
Final Test	ASE, Malaysia

Availability	
Samples:	Yes
Production:	Yes



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Green Package Qualification Stress Tests	#fails/#samples
Preconditioning Jedec Moisture Sensitivity Level 3 with IR reflow at 260 +/- 5°C (Prior to Temperature Cycle)	0/77
Temperature Cycle (-65°C/+150°C, 500 cycles)	0/77
Autoclave (100 %R.H./2 ATM, 121°C, 168 hrs)	0/77
Solderability	0/20
Assembly Yield	Equivalent to Standard Material set.
Construction Analysis	Complete / Pass

Qualification Date: July 22, 2004

For information on Tin Whiskers, visit the Legerity Green web page at:

<http://www.legerity.com/public.php?p=green>

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